

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-11. (Canceled).
12. (New) Microstructure comprising an adhesive layer between a substrate and a photo-patternable layer, the adhesive layer being photosensitive, arranged on at least one face of the substrate and being formed by a negative resin comprising at least one polymer of the elastomer family and at least one photo-initiating component, in solution in an aromatic solvent.
13. (New) Microstructure according to claim 12, wherein the polymer is a cyclic polyisoprene in solution in xylene.
14. (New) Microstructure according to claim 12, wherein the adhesive layer has a thickness comprised between 200nm and 10 $\mu$ m.
15. (New) Microstructure according to claim 12, wherein the photo-patternable layer is formed by at least one negative resin of epoxy type.
16. (New) Microstructure according to claim 12, wherein the photo-patternable layer has a thickness comprised between 50 $\mu$ m and 200 $\mu$ m.

17. (New) Microstructure according to claim 12, wherein the substrate is formed by a material selected from the group consisting of silicon, glass and plastics.

18. (New) Method of fabrication of a microstructure according to claim 12, comprising spreading and drying of an adhesive layer formed by a negative resin comprising at least one polymer of the elastomer family and at least one photo-initiating component, in solution in an aromatic solvent, before deposition of at least one photo-patternable layer of resin.

19. (New) Fabrication method according to claim 18, wherein the adhesive layer is exposed through a mask and developed, before deposition of the photo-patternable layer.

20. (New) Fabrication method according to claim 18, wherein the adhesive layer and the photo-patternable layer are exposed simultaneously through a mask.

21. (New) Fabrication method according to claim 20, wherein the photo-patternable layer and the adhesive layer are developed successively.

22. (New) Fabrication method according to claim 18, wherein at least two photo-patternable layers are developed simultaneously, after having been successively deposited and exposed through two different masks.